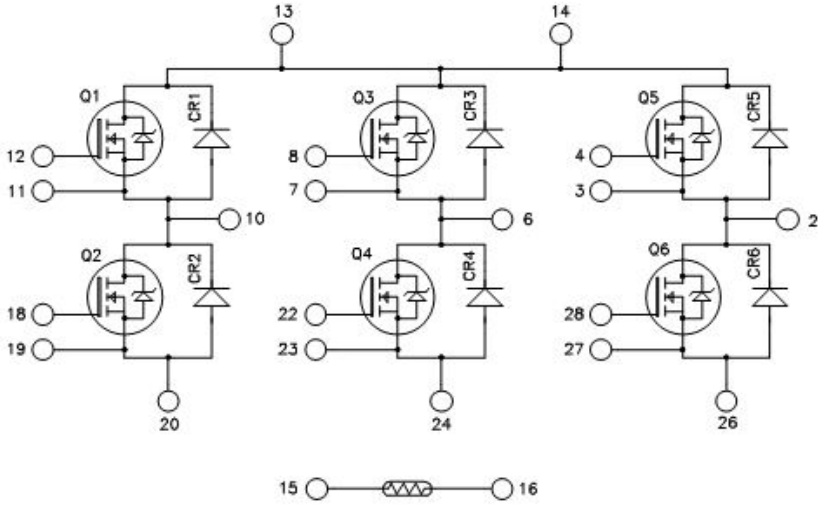
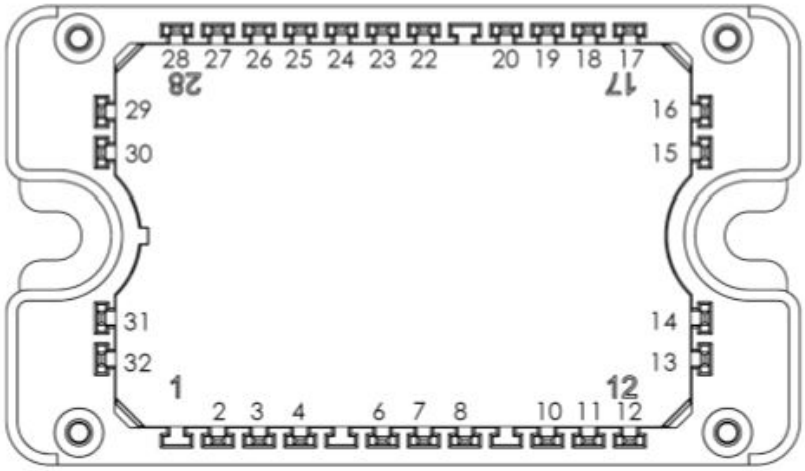
MSCSM120TAM31CT3AG

Three Phase Bridge SiC MOSFET Power Module

Product Overview

The MSCSM120TAM31CT3AG device is a three phase leg 1200V, 89A full silicon carbide (SiC) power module.





Notes:

- Pins 20/24/26 must be shorted together to perform a three phase bridge.
- All ratings at T_J = 25 °C, unless otherwise specified.

⚠ CAUTION These devices are sensitive to electrostatic discharge. Proper handling procedures must be followed.

Features

The following are key features of the MSCSM120TAM31CT3AG device:

- SiC Power MOSFET
  - High speed switching
  - Low $R_{DS(on)}$
  - Ultra low loss
- SiC Schottky Diode
  - Zero reverse recovery
  - Zero forward recovery
  - Temperature independent switching behavior
  - Positive temperature coefficient on V_F
- Very low stray inductance
- Kelvin source for easy drive
- Internal thermistor for temperature monitoring
- Aluminum nitride (AlN) substrate for improved thermal performance

Benefits

The following are the benefits of MSCSM120TAM31CT3AG device:

- High efficiency converter
- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- Solderable terminals for power and signal for easy mounting of PCB
- Low profile
- RoHS Compliant

Application

The MSCSM120TAM31CT3AG device is designed for the following applications:

- Welding converters
- Switched mode power supplies
- Uninterruptible power supplies
- EV motor and traction drive

1. Electrical Specifications

This section provides the electrical specifications of the MSCSM120TAM31CT3AG device.

1.1 SiC MOSFET Characteristics (Per SiC MOSFET)

The following table lists the absolute maximum ratings per SiC MOSFET of the MSCSM120TAM31CT3AG device.

Table 1-1. Absolute Maximum Ratings

Symbol	Parameter		Maximum Ratings	Unit
V_{DSS}	Drain-Source voltage		1200	V
I_D	Continuous drain current	T_C = 25 °C	89	A
		T_C = 80 °C	71	
I_{DM}	Pulsed drain current		180	
V_{GS}	Gate-Source voltage		−10/25	V
$R_{DS(on)}$	Drain-Source ON resistance		31	mΩ
P_D	Power dissipation	T_C = 25 °C	395	W

The following table lists the electrical characteristics per SiC MOSFET of the MSCSM120TAM31CT3AG device.

Table 1-2. Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min.	Typ.	Max.	Unit
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0V; V_{DS} = 1200V		—	10	100	µA
$R_{DS(on)}$	Drain–Source on resistance	V_{GS} = 20V I_D = 40A	T_J = 25 °C	—	25	31	mΩ
			T_J = 175 °C	—	40	—	
$V_{GS(th)}$	Gate threshold voltage	V_{GS} = V_{DS}; I_D = 1 mA		1.8	2.8	—	V
I_{GSS}	Gate–Source leakage current	V_{GS} = 20V; V_{DS} = 0V		—	—	150	nA

The following table lists the dynamic characteristics per SiC MOSFET of the MSCSM120TAM31CT3AG device.

Table 1-3. Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{GS} = 0V		—	3020	—	pF
C_{oss}	Output capacitance	V_{DS} = 1000V		—	270	—	
C_{rss}	Reverse transfer capacitance	f = 1 MHz		—	25	—	
Q_g	Total gate charge	V_{GS} = –5V/20V		—	232	—	nC
Q_{gs}	Gate-source charge	V_{Bus} = 800V		—	41	—	
Q_{gd}	Gate-drain charge	I_D = 40A		—	50	—	
$T_{d(on)}$	Turn-on delay time	V_{GS} = −5V/20V		—	30	—	ns
T_r	Rise time	V_{Bus} = 800V		—	30	—	
$T_{d(off)}$	Turn-off delay time	I_D = 50A		—	50	—	
T_f	Fall time	$R_{G(on)}$ = 8Ω $R_{G(off)}$ = 4.7Ω			25	—	
E_{on}	Turn-on energy	Inductive switching	T_J = 150 °C	—	0.99	—	mJ
E_{off}	Turn-off energy	V_{GS} = −5V/20V V_{Bus} = 600V I_D = 50A $R_{G(on)}$ = 8Ω $R_{G(off)}$ = 4.7Ω	T_J = 150 °C	—	0.66	—	
R_{Gint}	Internal gate resistance			—	0.88	—	Ω
R_{thJC}	Junction-to-case thermal resistance			—	—	0.38	°C/W

The following table lists the body diode ratings and characteristics per SiC MOSFET of the MSCSM120TAM31CT3AG device.

Table 1-4. Body Diode Ratings and Characteristics

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
V_{SD}	Diode forward voltage	V_{GS} = 0V; I_{SD} = 40A	—	4.0	—	V
		V_{GS} = −5V; I_{SD} = 40A	—	4.2	—	
t_{rr}	Reverse recovery time	I_{SD} = 40A; V_{GS} = −5V	—	90	—	ns
Q_{rr}	Reverse recovery charge	V_R = 800V; di_F/dt = 1000 A/µs	—	550	—	nC
I_{rr}	Reverse recovery current		—	13.5	—	A

1.2 SiC Schottky Diode Ratings and Characteristics (Per SiC Diode)

The following table lists the SiC diode ratings and characteristics per SiC diode of MSCSM120TAM31CT3AG device.

Table 1-5. SiC Schottky Diode Ratings and Characteristics

Symbol	Characteristic	Test Conditions		Min.	Typ.	Max.	Unit
V_{RRM}	Peak repetitive reverse voltage			—	—	1200	V
I_{RRM}	Reverse leakage current	V_R = 1200V	T_J = 25 °C	—	10	200	µA
			T_J = 175 °C	—	150	—	
I_F	DC forward current	—	T_C = 100 °C	—	30	—	A
V_F	Diode forward voltage	I_F = 30A	T_J = 25 °C	—	1.5	1.8	V
			T_J = 175 °C	—	2.1	—	
Q_C	Total capacitive charge	V_R = 600V		—	130	—	nC
C	Total capacitance	f = 1 MHz, V_R = 400V		—	141	—	pF
		f = 1 MHz, V_R = 800V		—	105	—	
R_{thJC}	Junction-to-case thermal resistance			—	—	0.9	°C/W

1.3 Thermal and Package Characteristics

The following table lists the thermal and package characteristics of the MSCSM120TAM31CT3AG device.

Table 1-6. Thermal and Package Characteristics

Symbol	Characteristics			Min.	Max.	Unit
V_{ISOL}	RMS isolation voltage, any terminal to case t =1 min, 50 Hz/60 Hz			4000	—	V
T_J	Operating junction temperature range			−40	175	°C
T_{JOP}	Recommended junction temperature under switching conditions			−40	T_{Jmax}–25	
T_{STG}	Storage temperature range			−40	125	
T_C	Operating case temperature			−40	125	
Torque	Mounting torque	To heatsink	M4	2	3	N.m
Wt	Package weight			—	110	g

The following table lists the temperature sensor NTC of the MSCSM120TAM31CT3AG device.

Table 1-7. Temperature Sensor NTC

Symbol	Characteristic		Min.	Typ.	Max.	Unit
R_{25}	Resistance at 25 °C	—	—	50	—	kΩ
$\Delta R_{25}/R_{25}$	—	—	—	5	—	%
$B_{25/85}$	T_{25} = 298.15K	—	—	3952	—	K
ΔB/B	—	T_C = 100 °C	—	4	—	%

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

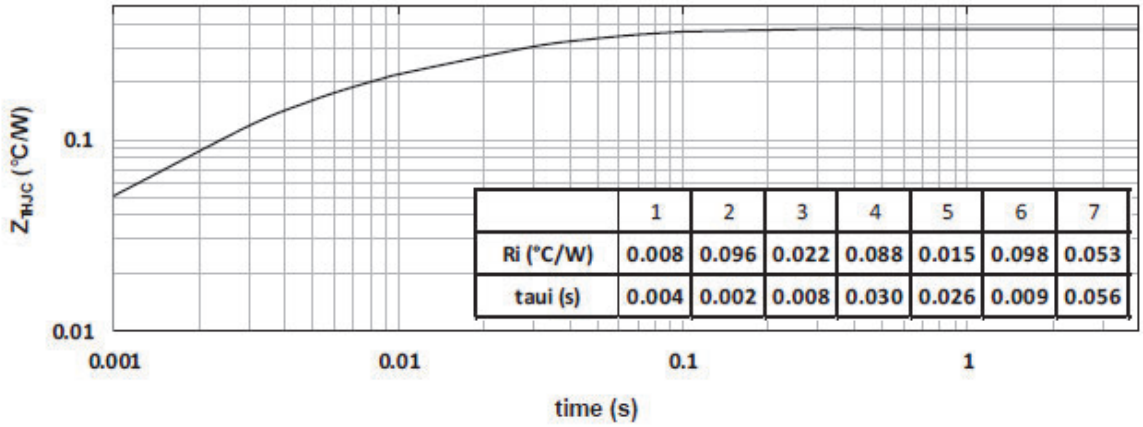
T: Thermistor temperature
R_T: Thermistor value at T

Note: See APT0406—Using NTC Temperature Sensor Integrated into Power Module for more information.

1.4 Typical SiC MOSFET Performance Curve

This section shows the typical SiC MOSFET performance curves of the MSCSM120TAM31CT3AG device.

Figure 1-1. Maximum Thermal Impedance



	1	2	3	4	5	6	7
Ri (°C/W)	0.008	0.096	0.022	0.088	0.015	0.098	0.053
taui (s)	0.004	0.002	0.008	0.030	0.026	0.009	0.056

Figure 1-2. Output Characteristics, T_J = 25 °C

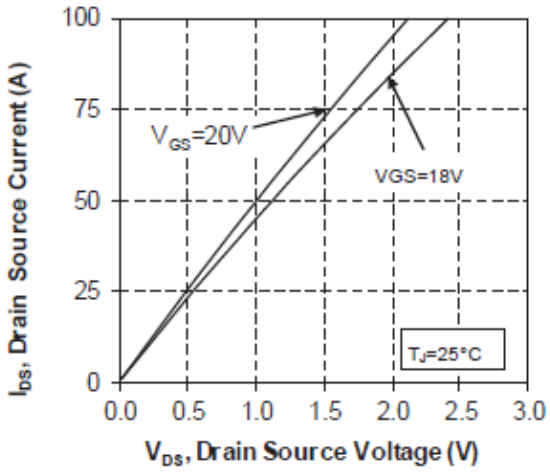


Figure 1-3. Output Characteristics, T_J = 175 °C

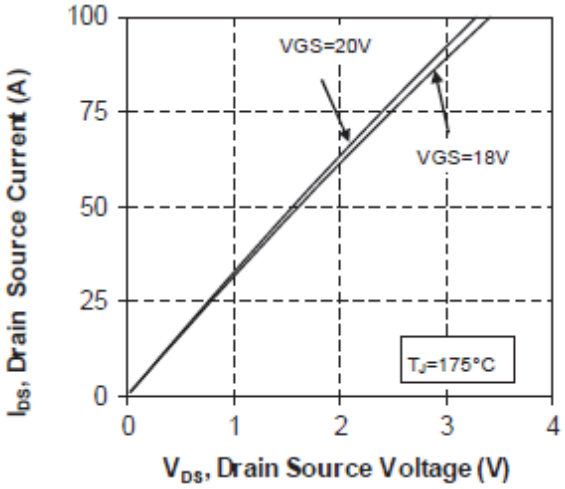


Figure 1-4. Normalized $R_{DS(on)}$ vs. Temperature

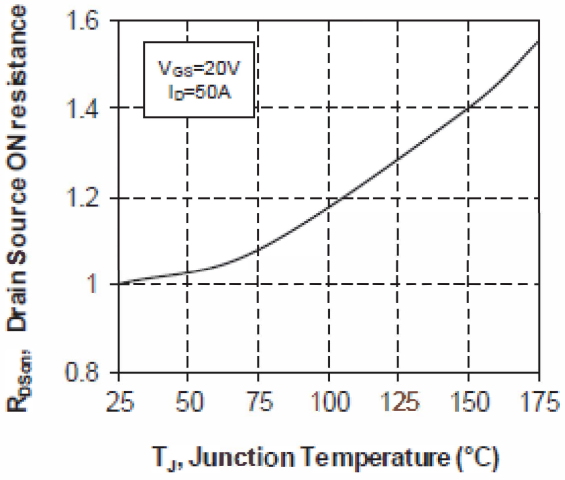


Figure 1-5. Transfer Characteristics

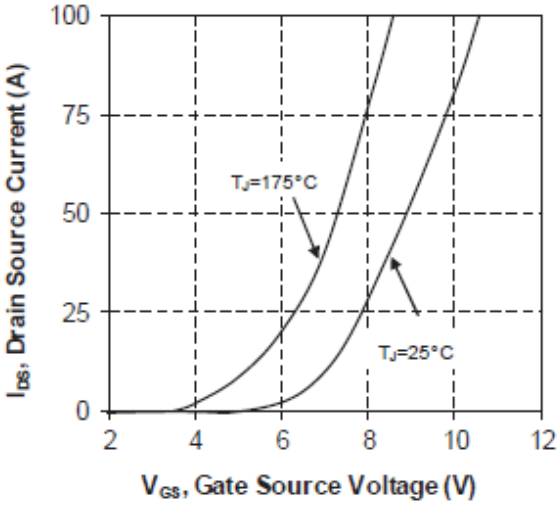


Figure 1-6. Switching Energy vs. Rg

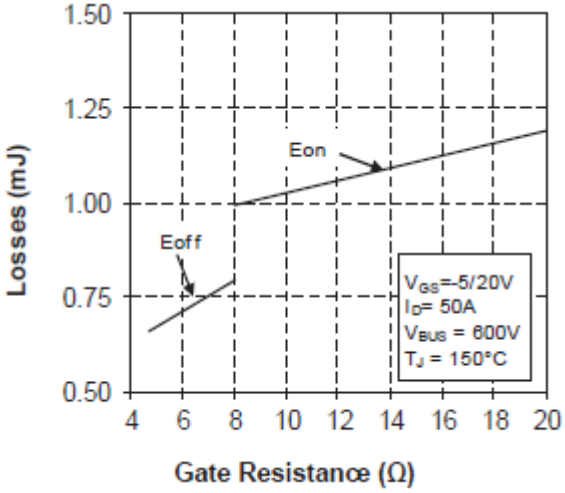


Figure 1-7. Switching Energy vs. Current

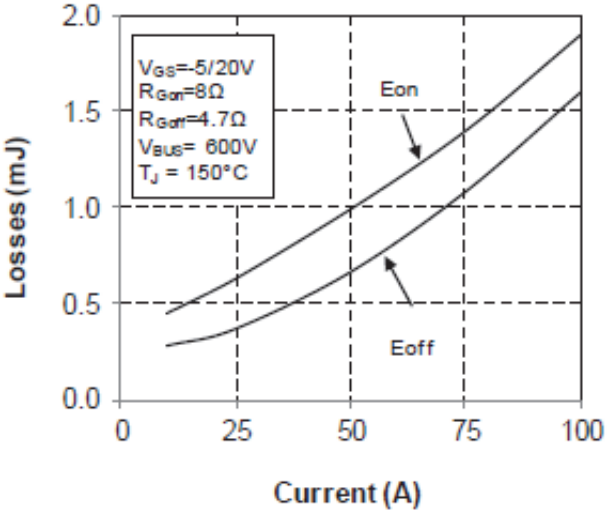


Figure 1-8. Capacitance vs. Drain Source Voltage

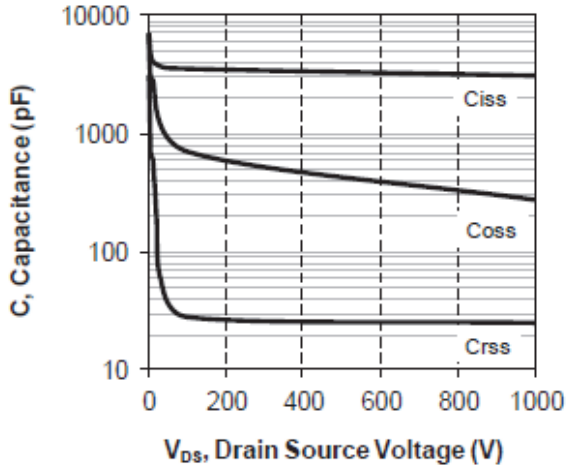


Figure 1-9. Gate Charge vs. Gate Source Voltage

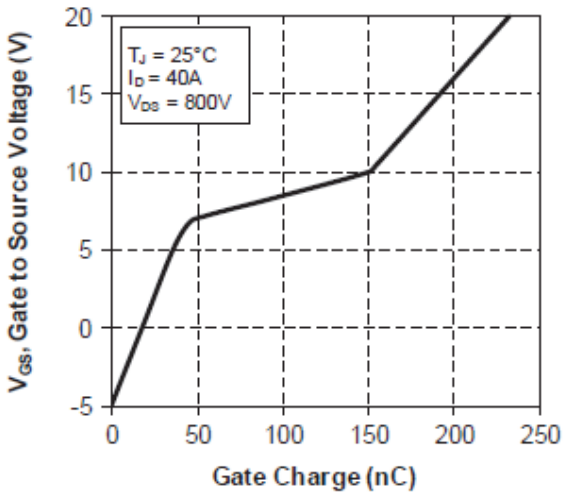


Figure 1-10. Body Diode Characteristics, T_J = 25 °C

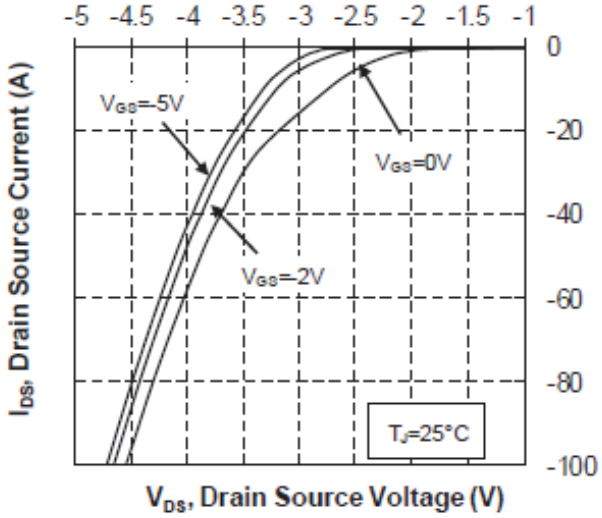


Figure 1-11. 3rd Quadrant Characteristics, T_J = 25 °C

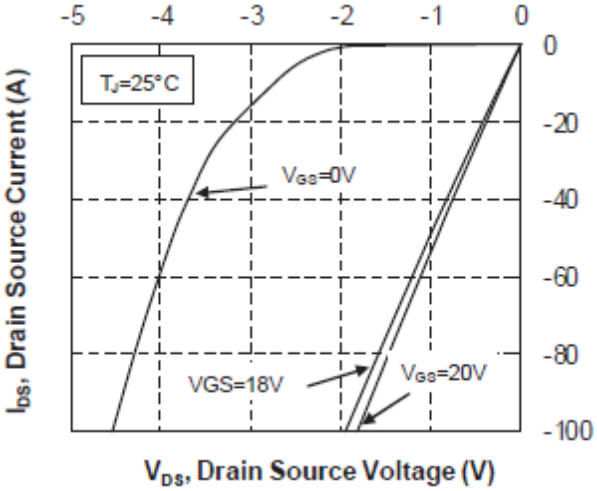


Figure 1-12. Body Diode Characteristics, T_J = 175 °C

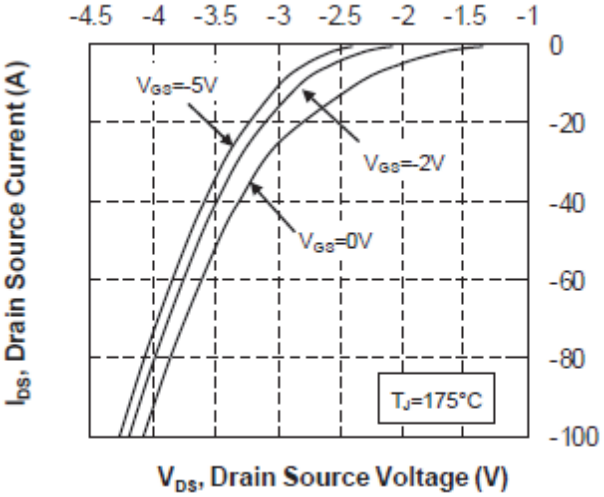


Figure 1-13. 3rd Quadrant Characteristics, T_J = 175 °C

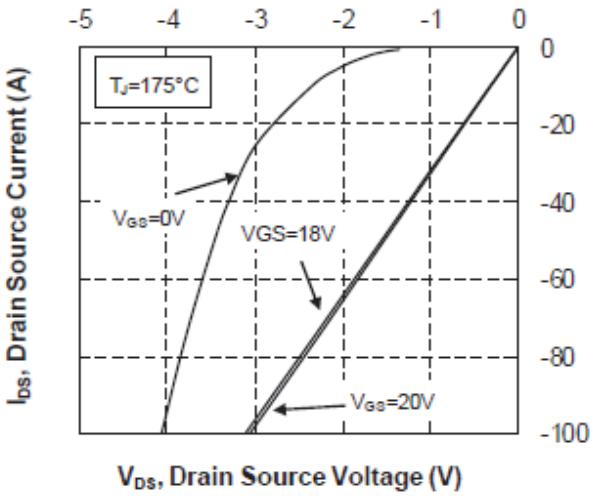
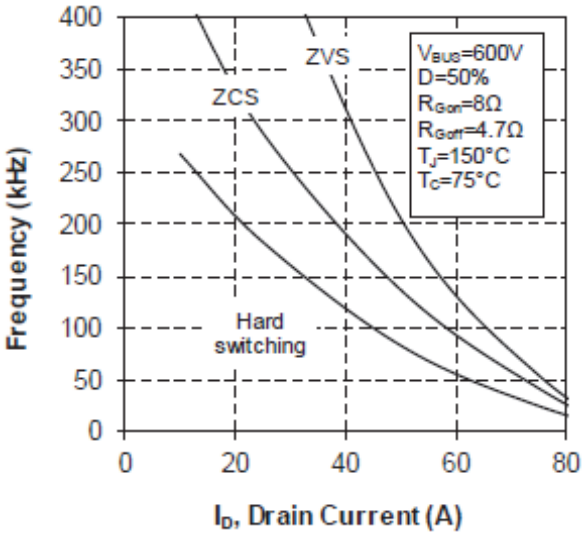


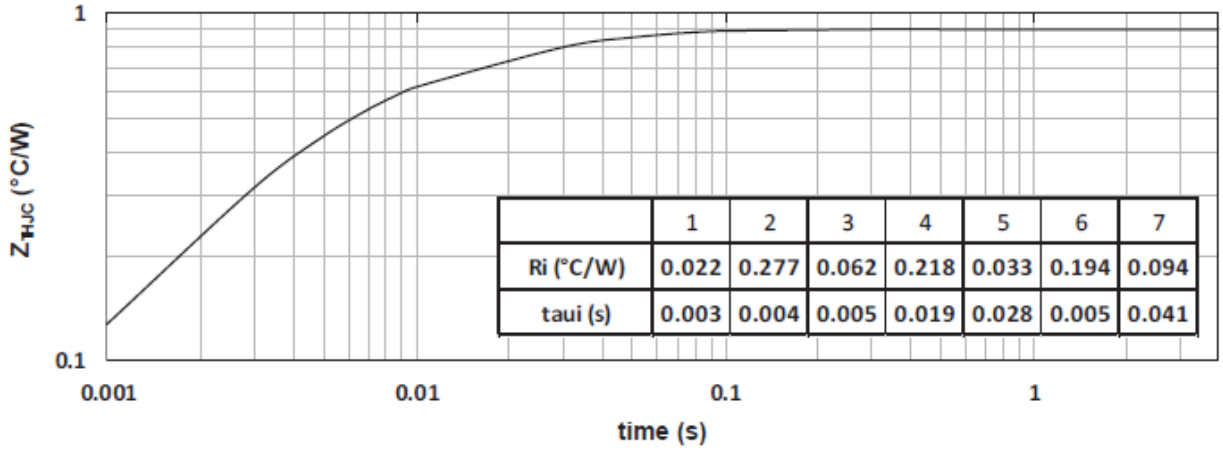
Figure 1-14. Operating Frequency vs Drain Current



1.5 Typical SiC Diode Performance Curves

This section shows the typical SiC diode performance curves of the MSCSM120TAM31CT3AG device.

Figure 1-15. Maximum Thermal Impedance



	1	2	3	4	5	6	7
Ri (°C/W)	0.022	0.277	0.062	0.218	0.033	0.194	0.094
taui (s)	0.003	0.004	0.005	0.019	0.028	0.005	0.041

Figure 1-16. Forward Characteristics

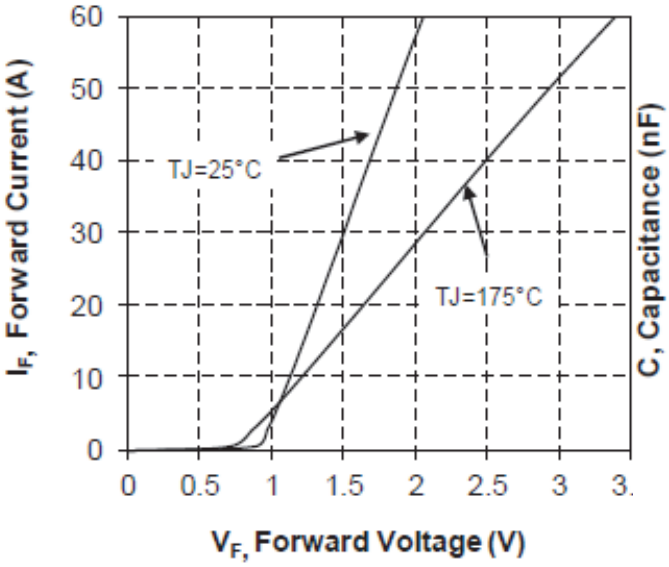
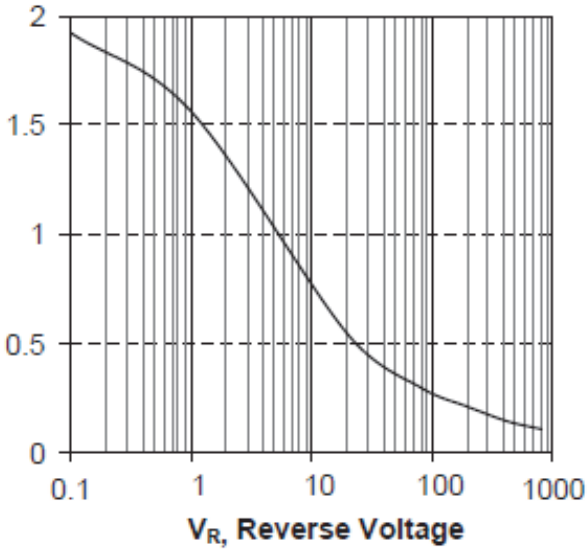


Figure 1-17. Capacitance vs. Reverse Voltage



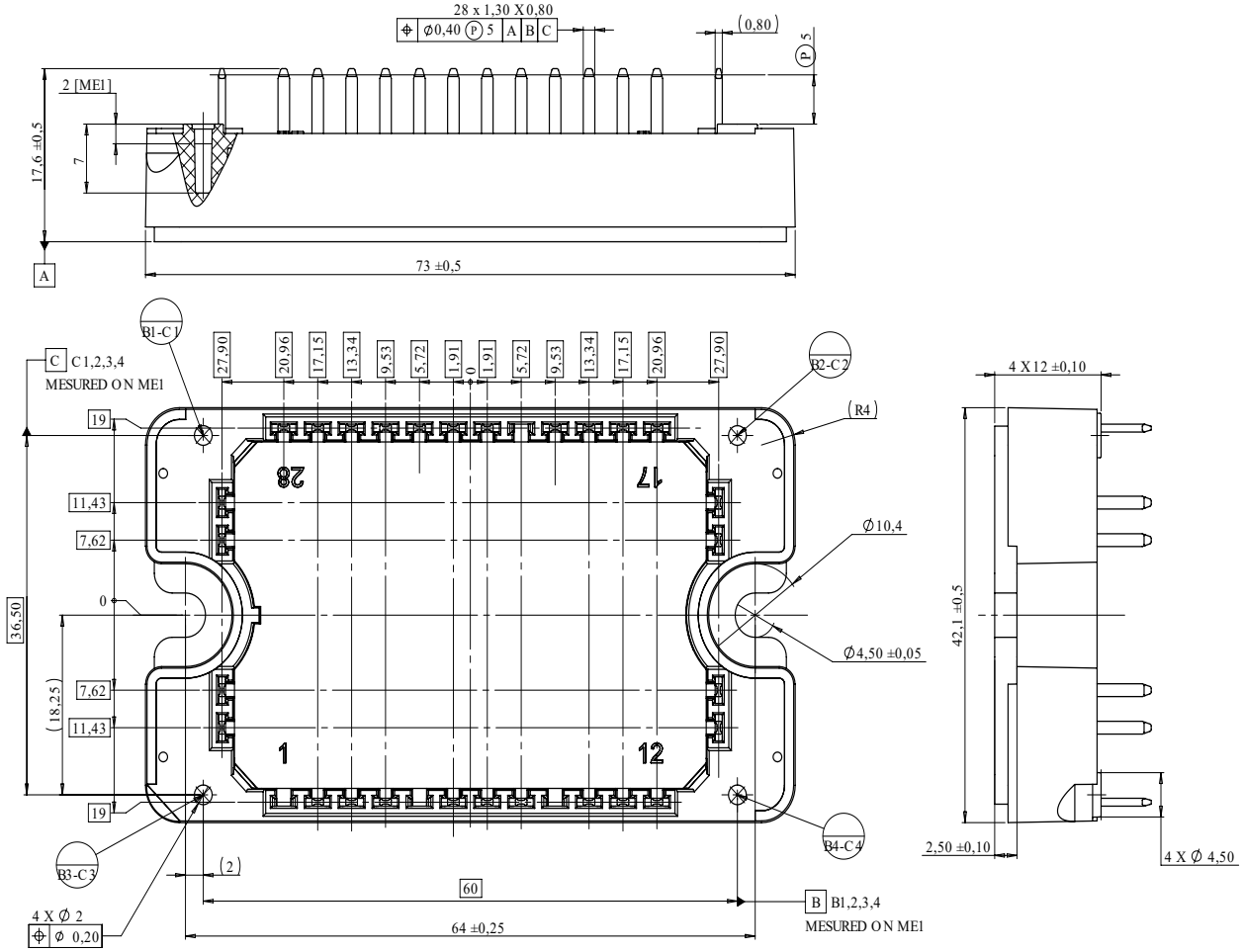
2. Package Specifications

The following section shows the package specification of the MSCSM120TAM31CT3AG device.

2.1 Package Outline

The following figure shows the package outline drawing of the MSCSM120TAM31CT3AG device. The dimensions in the following figure are in millimeters.

Figure 2-1. Package Outline Drawing



Note: See AN3500—Mounting Instructions for SP1F and SP3F Power Modules for more information.

3. Revision History

The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

Revision	Date	Description
A	10/2022	The following is the list of changes made in revision A of the document: • The document was migrated to the Microchip template. • The document number was updated to DS00004774A from MSCC-0344-DS-01070-1.0-0120.
1.0	01/2020	Initial Revision

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